ABSOCIATION CONNECTING LECTRONICS INDUSTRIES® International and Pan-American co	ourn. Illinois. All rights reserved un	der both This docum level parts,	ent is a declaratio the declaration en	n of the substance compasses all low	es within the manufacture ver level materials for wh	er listed item. Note: hich the manufacture	if the item is an a er has engineering	ssembly with lower responsibility.			
IPC Web Site for Information on I http://www.ipc.org/IPC-175x	PC-1752 Standard	Form Type * Distribute		ration Class * 6 - RoHS Yes/No	o, Homogeneous Materia	als and Mfg Informa	s and Mfg Information				
Supplier Information											
Company name*	Company unique ID		Unique ID Authority			Response Date*					
onsemi								2023-06-08			
Contact Name	Title - Contact		Phone - Contact*			Email - Contact*					
Product-Env-Stewards	Product Enviro Compliance		NA			Product-Env-Stewards@onsemi.com					
Authorized Representative*	Representative* Title - Representative		Phone - Representative*			Email - Representative*					
Product-Env-Stewards Product Enviro Compliance			NA			Product-Env-Stewards@onsemi.com					
Requester Item Number Mfr Item	Number Mfr Item Name		Effective Date	Version	Manufacturing Site	Weight*	UOM	Unit Type			
FODM1	008 LSOP4 TR		2023-06-08		CP7	117.85945	mg	Each			
Manufacturing Proccess Information											
Terminal Plating / Grid Array Material T	erminal Base Alloy J-	STD-020 MSL Rating	Peak Proces	s Body Temperat	ure Max Time at Peak	Temperature Num	ber of Reflow Cy	cles			
Matte Tin (Sn) - annealed CU Alloy 1			260	С	30	seconds 3					
Comments											
evel 1 - maximum time at peak temperature during sol	dering is 10-30 seconds										
For more information regarding material composition	please refer to page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed			
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).							
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of			
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted			
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all			
Exemption List Version	EL-2011/534/EU							
Declaration Signature								
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the			
Supplier Digital Signature Ra	stislav Drska	Le						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Chip	0.04429	mg	В	Gallium Arsenide (AsGa)	1303-00-0		0.0437	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0001	mg
			Supplier	Silicon (Si)	7440-21-3		0.0001	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0004	mg
Coating	4.0	mg	Supplier	Silica (SiO2)	14464-46-1		4	mg
Die Attach	0.26	mg	Supplier	Silver (Ag)	7440-22-4		0.2	mg
			Supplier	Phenolic Resin-2	54208-63-8		0.02	mg
			Supplier	Dicyandiamine	461-58-5		0.01	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.02	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.01	mg
Lead Frame	1.808	mg	Supplier	Silver (Ag)	7440-22-4		0.268	mg
			Supplier	Copper (Cu)	7440-50-8		1.54	mg
Mold Compound-Black	74.042	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		9.662	mg
			Supplier	Carbon Black (C)	1333-86-4		0.74	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		6.66	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		5.18	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		51.8	mg
Mold Compound-White	35.0025	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		7.0005	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		24.5017	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		3.5002	mg
lating	2.5	mg	Supplier	Tin (Sn)	7440-31-5		2.5	mg
PTR Die	0.13266	mg	Supplier	Boron (B)	7440-42-8		0.0007	mg
			Supplier	Silicon (Si)	7440-21-3		0.13	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0007	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0013	mg
Wire Bond - Au	0.07	mg	Supplier	Gold (Au)	7440-57-5		0.07	mg